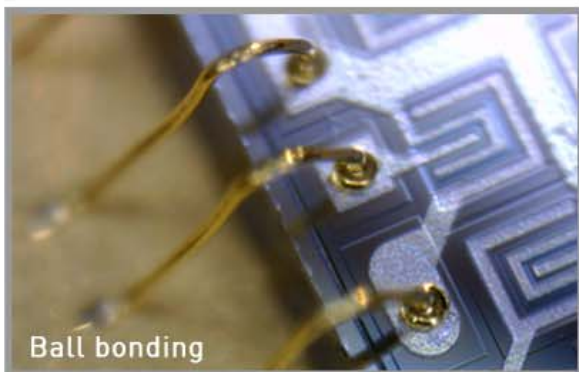




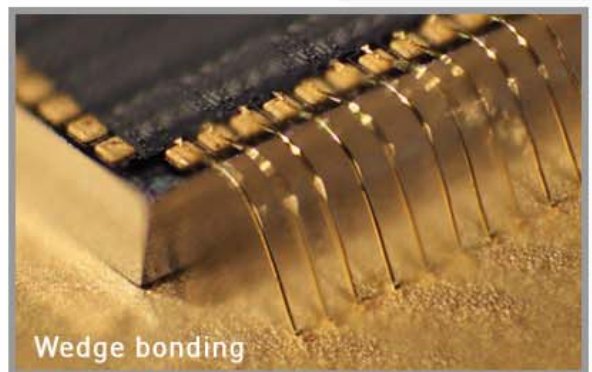
TPT Wirebonder Overview



Bonder	HB05	HB10	HB16	HB30
Type	Manual	Semiautomatic	Semiautomatic	Semiautomatic
Motorized axis	-	Z-Axis	Z- & Y- Axis	Z- & Y- Axis
Auto Height Setup	-	Yes	Yes	Yes
Loop Control	-	Height Control	Loop Profil	Loop Profil
Control Panel	4" TFT	6,5" Touch Screen	6,5" Touch Screen	6,5" Touch Screen
Wire Size	17 μ -75 μ	17 μ -75 μ	17 μ -75 μ	100 μ -500 μ
Program Storage	20	100	100	100
Ultrasonic Power	5 Watt	5 Watt	5 Watt	20 Watt
Bondforce	130 cN	150 cN	150 cN	1800 cN
Pick & Place Option	Yes	Yes	Yes	-
Pull Tester Option	-	Yes	Yes	-
Copper Bonding Option	Yes	Yes	Yes	-
Spotlight Target Option	Yes	Yes	Yes	Yes



Ball bonding



Wedge bonding